

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance **E-Mail** Product.Compliance@molex.com

Part Information

Part Number 0353121160 **Part Weight** 1.001G

Part Name 2.5 PITCH W/B CONN WAFER ASSY

Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
2.5 PITCH W/B CONN WAFER ASSY	Assembly		100	1.001
2.5 PITCH W/B CONN WAFER	Component		65.9341	0.66
PA66-GF20	Material		65.9341	0.66
PA66	Substance		35.6044	0.3564
GF-Fibre	Substance		13.1868	0.132
Flame Retardant, ISO 1043-4 FR(17)	Substance		11.2088	0.1122
Antimonytrioxide	Substance	1309-64-4	4.6154	0.0462
Further Additives, not to declare	Substance	system	1.3187	0.0132
0.635 SQ WIRE PIN(PLATED)	Assembly		34.0659	0.341
. SQ WIRE PIN(UNPLAT)	Component		34.0659	0.341
C2700	Material		34.0659	0.341
Copper	Substance	7440-50-8	22.1429	0.22165
Zinc (metal)	Substance	7440-66-6	11.906	0.11918

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Lead	Substance	7439-92-1	0.0085	0.000085
Iron	Substance	7439-89-6	0.0085	0.000085

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	C2700	*Note	250	Yes
Antimonytrioxide	PA66-GF20	*Note	70,000	Yes
copper	C2700	*Note	650,000	Yes
glass, oxide, chemicals	PA66-GF20	*Note	200,000	Yes

*Note: For GADSL substance declarable/prohibited threshold values, please reference <http://www.gadsl.org/>

Exemptions

Part Name	Exemption
C2700	44 Concentration within acceptable GADSL limits


HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PA66-GF20	900	170,000	Yes
Bromine and Chlorine combined	PA66-GF20	1,500	170,000	Yes

China ROHS Declaration Information

Part Number 0353121160		Hazardous Substances					
Part Name 2.5 PITCH W/B CONN WAFER ASSY							
Part Information							
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE

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Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
2.5 PITCH W/B CONN WAFER ASSY	O	O	O	O	O	O
2.5 PITCH W/B CONN WAFER	O	O	O	O	O	O
0.635 SQ WIRE PIN(PLATED)	O	O	O	O	O	O
. SQ WIRE PIN(UNPLAT)	O	O	O	O	O	O

Process Information

Component Plating / Surface Finish	SnCu
Termination Base Alloy	Brass
Solder Alloy	SnAgCu
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 24, 2021